



ZFV

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: **SUNOHARA, Masahiro, et al.**

Group Art Unit: **2826**

Serial No.: **10/756,763**

Examiner: **Alexander O. WILLIAM**

Filed: **January 14, 2004**

P.T.O. Confirmation No.: 1523

FOR: AN ELECTRONIC PARTS PACKAGING STRUCTURE IN WHICH A SEMICONDUCTOR CHIP IS MOUNTED ON A WIRING SUBSTRATE AND BURIED IN AN INSULATION FILM (As Amended)

AMENDMENT UNDER 37 CFR §1.111

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

February 24, 2006

Sir:

In response to the Office Action dated **December 16, 2005**, please amend the above-identified application as follows:

Amendments to the Title are reflected on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 3 of this paper.

Remarks/Arguments begin on page 10 of this paper.

AMENDMENTS TO THE TITLE:

The title of the present invention has been changed to read as follows:

--An Electronic Parts Packaging Structure in which a Semiconductor Chip is mounted on a
Wiring Substrate and buried in an Insulation Film--